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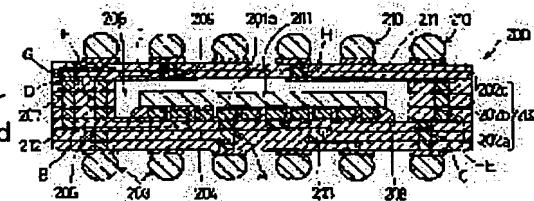
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(54) MOUNTING MEMBER OF ELECTRONIC COMPONENT, METHOD OF MANUFACTURING MOUNTING MEMBER OF ELECTRONIC COMPONENT, AND SECONDARY MOUNTING STRUCTURE OF MOUNTING MEMBER

(57)Abstract:

PROBLEM TO BE SOLVED: To reduce the size of a product by reducing mounting area.

SOLUTION: External connection terminals 203, 210, connected electrically with an electronic component 201, are disposed on both surfaces of a package board 202 where the electronic component 201 is mounted and arranged in the inside and both surfaces are closed, and a mounting member 200 is constituted, so that external connection terminals 210 are arranged also on the upper surface part of the package board 202 positioned upward of the electronic component 201.



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